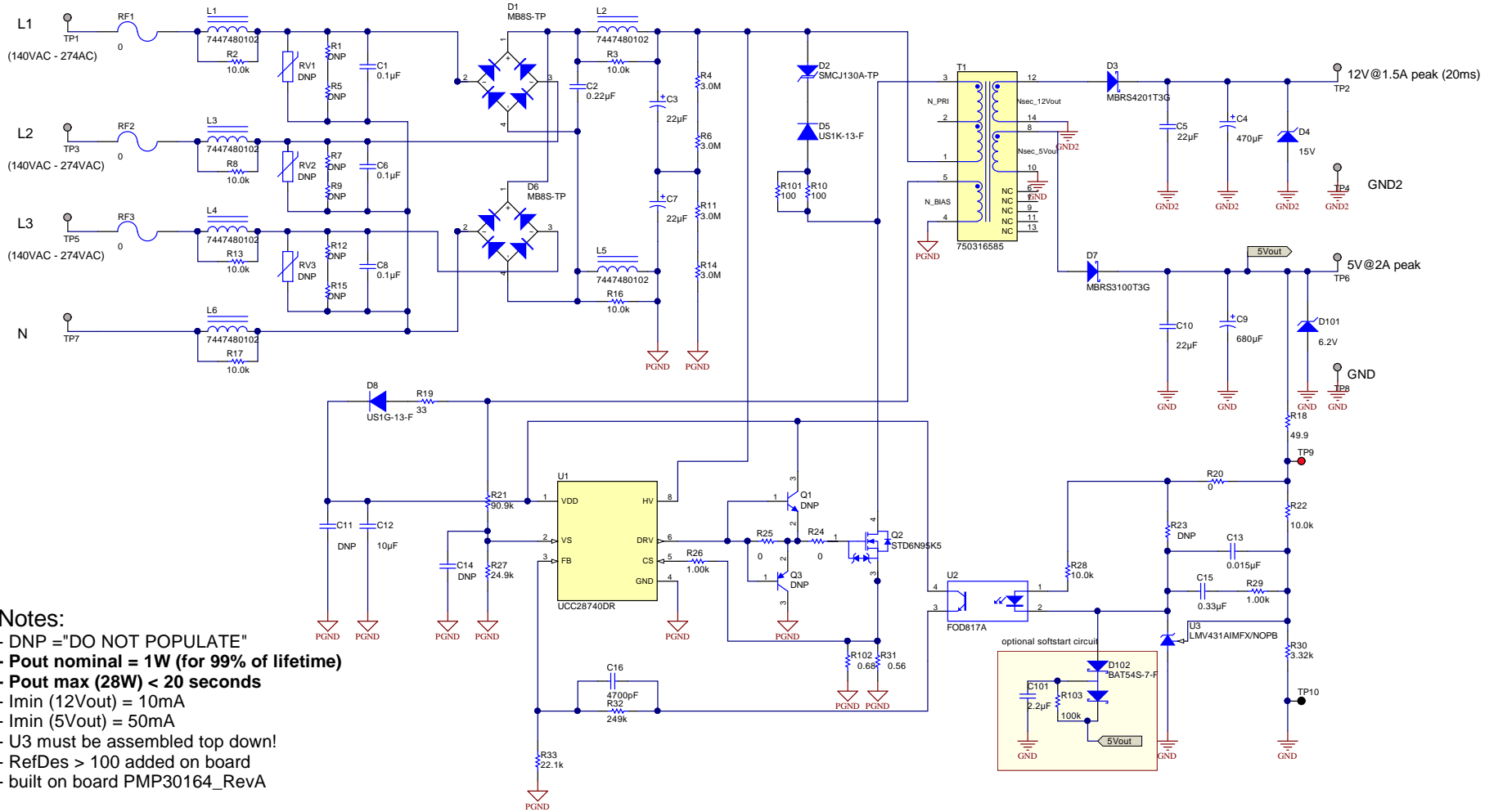


Vin\_start\_DC=200VDC  
 Vin\_min\_DC=250VDC  
 Vin\_nom\_DC=560VDC  
 Vin\_max\_DC=670VDC



**Notes:**

- DNP ="DO NOT POPULATE"
- Pout nominal = 1W (for 99% of lifetime)
- Pout max (28W) < 20 seconds
- Imin (12Vout) = 10mA
- Imin (5Vout) = 50mA
- U3 must be assembled top down!
- RefDes > 100 added on board
- built on board PMP30164\_RevA

Orderable: EVM orderable	Designed for: Public Release	Mod. Date: 12/13/2016
TID #: N/A	Project Title: 3 phase Flyback	
Number: PMP30164	Rev: B	Sheet Title:
SW Rev: Version control disabled	Assembly Variant: No Variations	Sheet: 2 of 3
Drawn By:	File: PMP30164_RevB_SchDoc	Size: B
Engineer: F. Mueller	Contact: http://www.ti.com/support	

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